

Product Change Notification / NTDO-04NIFV893

Product Change Notification	OII / NIDO-04NJEIO	593 	
Date:			
23-Feb-2023			
Product Category:			
Wireless IC			
PCN Type:			
Manufacturing Change			
Notification Subject:			
CCB 5029 Final Notice: Qualifi device family available in 56L			
Affected CPNs:			
NTDO-04NJEY893_Affected_ NTDO-04NJEY893_Affected_			
Notification Text:			
PCN Status:Final Notification			
PCN Type:Manufacturing Cha	nge		
Microchip Parts Affected:Plea Note: For your convenience N	•		
Description of Change :Qualification device family available in 56L		•	
Pre and Post Change Summa	ry:		
	Pre Change	Post Change	

Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)				
Wire Material	PdCu	PdCu				
Die Attach Material	EN-4900GC	EN-4900GC				
Molding Compound Material	CEL-9240HF10AC	G700LA				
Lead-Frame Material	C194	C194				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying G700LA as a new molding compound material.

Change Implementation Status:In Progress

Estimated First Ship Date:March 28, 2023 (date code: 2313)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2022			>	February 2023			March 2023							
Workweek	1 4	1 5	1 6	1 7	1 8		5	6	7	8	9	1 0	1 1	1 2	1 3
Initial PCN Issue Date		Х													
Qual Report Availability										Х					
Final PCN Issue Date										Х					
Estimated Implementation Date															Х

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:April 7, 2022: Issued initial notification

February 23, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 28, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_NTDO-04NJEY893_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

 $NTDO-04NJEY893-CCB\ 5029\ Final\ Notice: Qualification\ of\ G700LA\ as\ a\ new\ mold\ compound\ material\ for\ selected\ IS168xS\ device\ family\ available\ in\ 56L\ VQFN\ (7x7x0.9mm)\ assembled\ at\ ASCL\ assembly\ site.$

Affected Catalog Part Numbers (CPN)

IS1683S-151-TRAY IS1683S-151 IS1681S-151-TRAY IS1681S-151 IS1684S-151

Date: Thursday, February 23, 2023